

Session 1: 5G als Technologie für Kommunikation und Positionierung



»5G Hardware«

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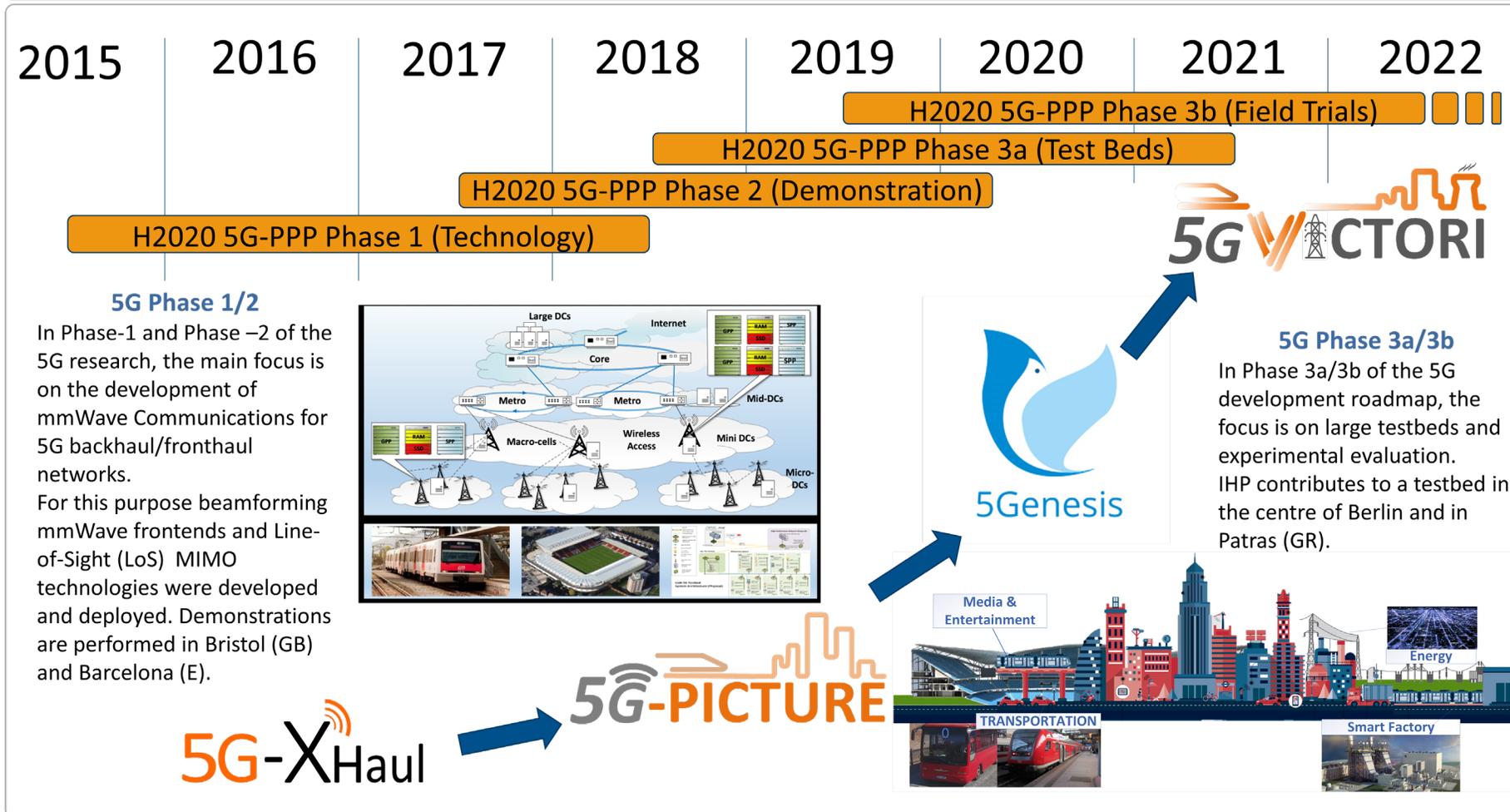
5G – Herausforderungen: Die Key Performance Indicators (KPI) der 5G IA



- 1000 times higher mobile data volume per geographical area.
- 10 to 100 times more connected devices.
- 10 times to 100 times higher typical user data rate.
- 10 times lower energy consumption.
- End-to-End latency of < 1ms.
- Ubiquitous 5G access including in low density areas.
- Reduction of the network management OPEX by at least 20% compared to today

Source: <https://5g-ppp.eu/kpis/>

5G – IHPs European Project Portfolio



Strategien die KPI zu erreichen (Shannon Kanalkapazität)



1. *Höhere Bandbreite*

- *Hohe Trägerfrequenzen*

2. *Besseres Signal zu Rausch-Verhältnis (SNR)*

- *Kleine Zellen – reduzierte Entfernung*
- *Besser Hardware*
 - *LNA-Rauschzahl*
 - *PA-Linearität und Ausgangsleistung*
 - *Leistungseffizienz (PA+Transceiver)*
 - *PLL-Phasenrauschen*
 - *...*

3. *Effiziente Ausnutzung der Kanalkapazität*

- *Waveforms*
- *Signalverarbeitung*
- *Protokolle*

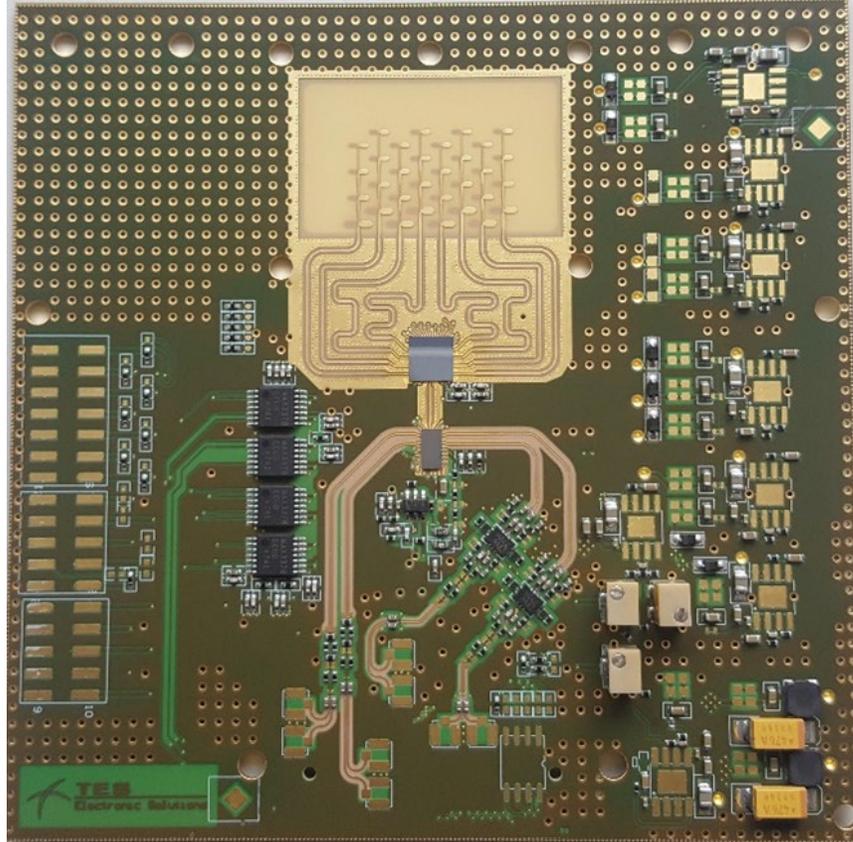
4. *Multiplexing*

- *(Hybrid) Beamforming*
- *(Line-of-Sight) MIMO*
- *Orbital Angular Momentum (OAM)*
- *Polarization*
- *...*

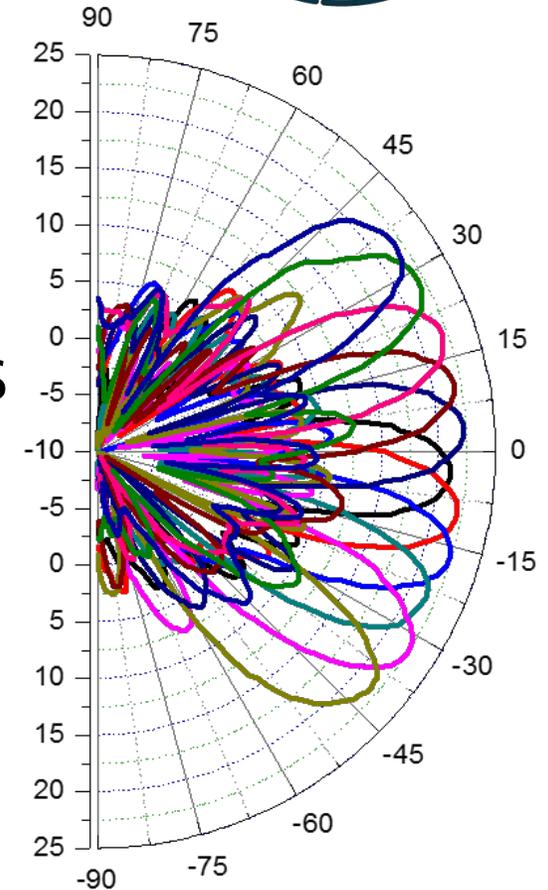
Strategien die KPI zu erreichen (mmWave Beamforming)



60 GHz beam steering frontend Module with 8-channel vector modulator chip and up/down converter chip (both developed & fabricated by IHP)



Measured beam pattern with 4x8-element Uniform Linear Array (ULA) antenna (developed by TES Electronic Solutions)



Strategien die KPI zu erreichen (WaveForms & Protocols)

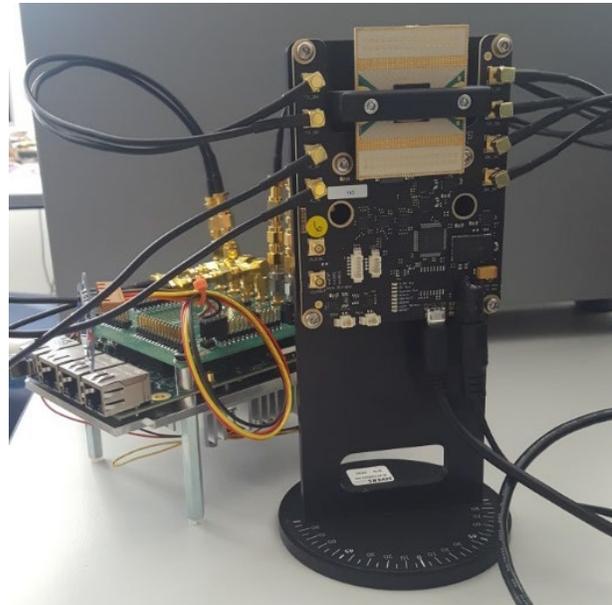
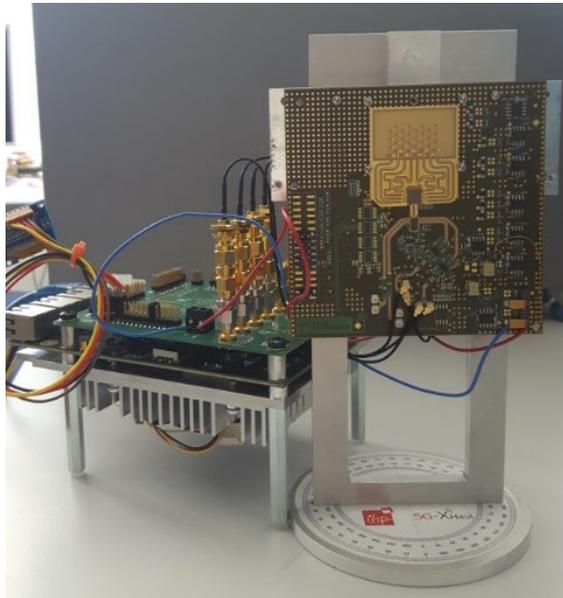


- IHP digiBackBoard platform

Successfully used in several projects (e.g. proWiLAN, fast-Secure, 5G-Xhaul, 5G-Picture, 5Genesis, Wortecs, ...)



- mmWave (60-GHz) beamforming demonstrator with different AFEs



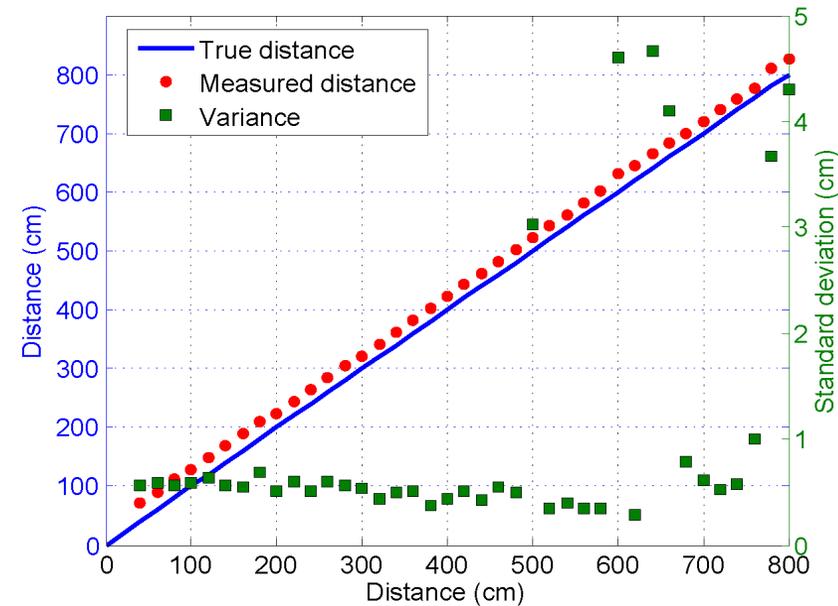
mmWave High Data-Rate Communication & Localization



- Simultaneous Data Transmission and Ranging @ 60 GHz demonstrated
- Data rate: ca 3.6 Gbit/s; Ranging Precision: ca. 1 cm
- Best Demonstrator Award at „11th IEEE Workshop on Positioning, Navigation and Communication (WPNC 2014)“, (M. Ehrig, Mar. 2014)



Demonstrator Setup



Measurement Results

5G Hardware: Status



■ Timeline 5G roll-out

- 1st step: Frequency bands < 6 GHz (e.g., 3.5 GHz)
 - Hardware solutions close to existing 2 GHz components
 - New: Massive MIMO (antenna arrays) on BTS side
- 2nd step: mm-wave bands (28 GHz range for first prototypes)
 - Full technical solutions still under research/development

■ Different scenarios

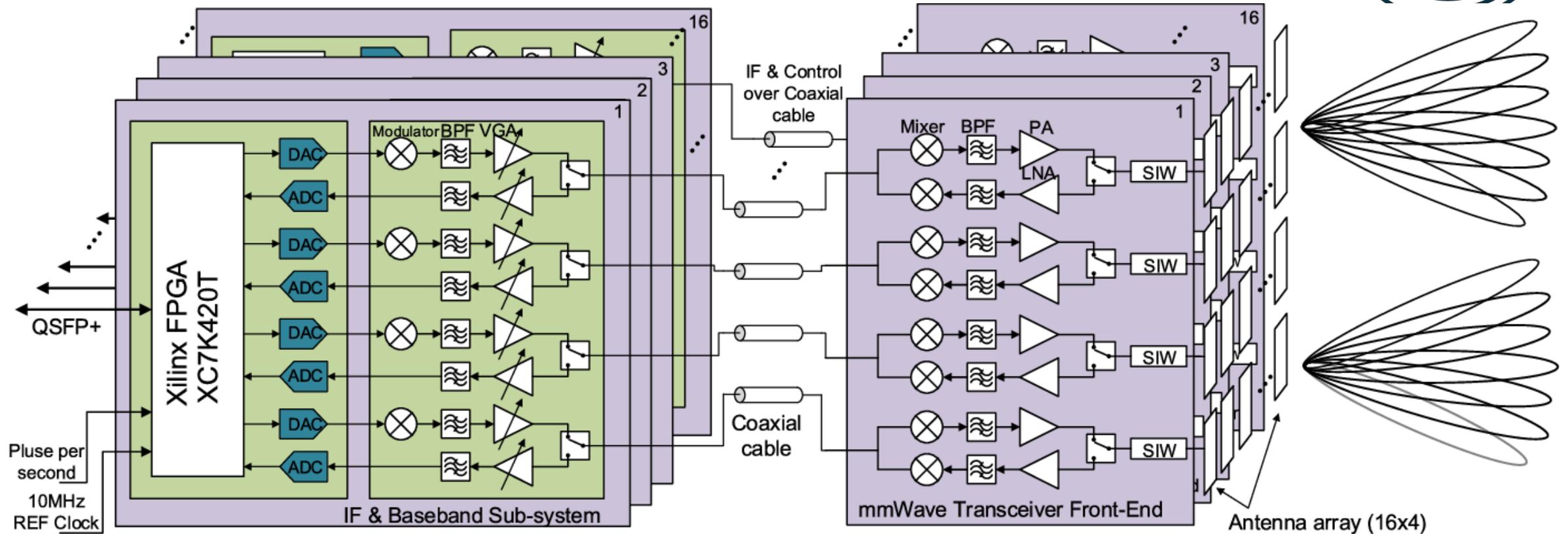
- Handset / base station (BTS) / backbone

Starting Point: The 4G Base Station



- Output power determined by radio link budget
 - typ. 100 W peak
- Antenna via cable
- Target: Energy efficiency & linearity
 - most critical component: Power amplifier (PA)
- Digital linearization
(Digital Predistortion, DPD)

The MIMO Challenge (I)



Source: Yang, Binqi et al. "Digital Beamforming-Based Massive MIMO Transceiver for 5G Millimeter-Wave Communications." IEEE Transactions on Microwave Theory and Techniques 66 (2018): 3403-3418.

The MIMO Challenge (II)



- Complexity of system and packaging
 - Antenna dimensions governed by $\lambda/2$ pitch between element patches (3 GHz -> 5 cm)
 - Integration of antenna with radio front-end attractive/indispensable
- Measurements: only air interface on antenna side

The MIMO Challenge (III)



- Efficiency & linearity
 - Beamforming:
max. radiated power = sum of all transmitters
 - Massive MIMO = increasing number of patches
 - Output power required per channel reduces
– holds for RF power consumption as well
 - DC power for DAC/ADC and digital linearization (DPD) grows
 - even more critical for large bandwidths, due to high-speed digital signal processors
- In contrast to present BTS - limits the number of parallel digital channels

The MIMO Challenge (IV)



- Solutions under investigation
 - Hybrid MIMO system
 - Form analog subgroups (beam steering by phase shifters etc.)
 - Less power-hungry signal digital circuitry
 - Simplify linearization (analog approaches)

The mm-Wave Challenge



- Antenna size shrinks (pitch patches @ 30 GHz: 5 mm)
 - reduced form factor of transceiver needed
- Semiconductor circuit performance changes
 - Degradation in output power and efficiency
 - Higher cost, less maturity (in general)
- Which semiconductor technology for BTS radio front-ends?
 - Criteria: Output power and efficiency, integration capabilities, cost
 - RF-CMOS, SiGe, GaAs, GaN
 - Hetero-integration?

The Efficiency Challenge (I)

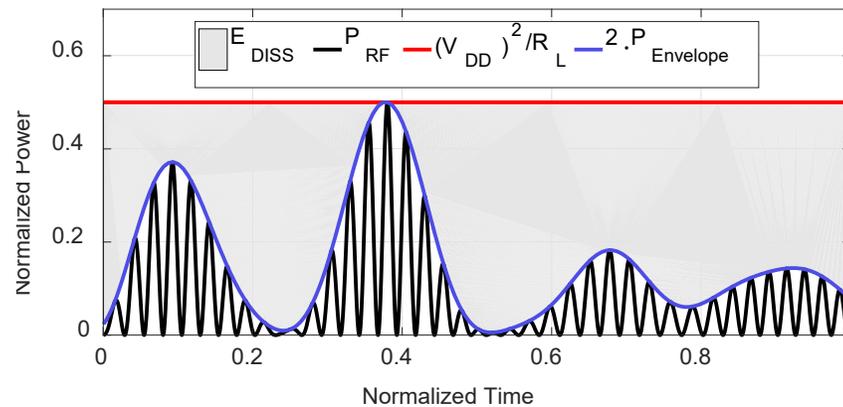


- Broadband modulation schemes: peak $P(\text{out}) \gg$ average $P(\text{out})$ (PAPR typically 10 dB)
- Conventional PAs: low power-added efficiency (PAE)
- Alternatives
 - Doherty PA

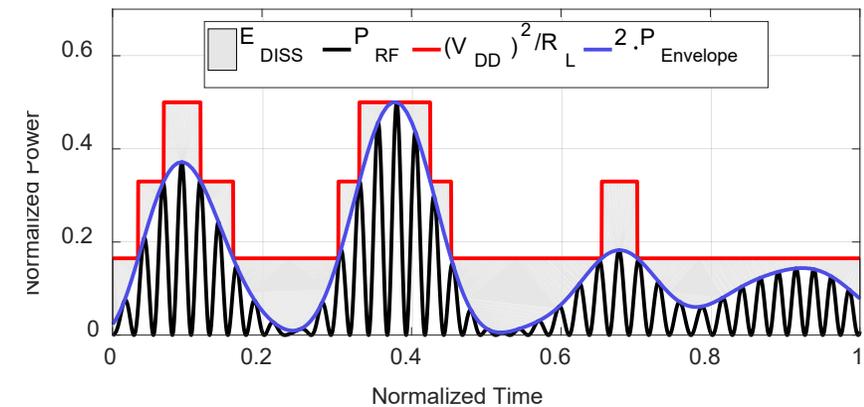
The Efficiency Challenge (II)



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 - Envelope Tracking



Source: FBH



The Efficiency Challenge (III)



- Broadband modulation schemes: peak $P(\text{out}) \gg$ average $P(\text{out})$ (PAPR typically 10 dB)
- Conventional PAs: low power-added efficiency (PAE)
- Alternatives
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- High bandwidth \rightarrow high-speed DSPs \rightarrow high energy consumption

FMD Expertise and Services for 5G



- Comprehensive competence on semiconductor and circuit level
 - SiGe and GaN components, < 6 GHz and up to >100 GHz
 - Circuit concepts (energy-efficient transceivers, mm-waves)
 - Integration on wafer and module level
- ...on system level
 - FPGA platform for rapid prototyping & demonstration (+ A/D & D/A converter)
 - Base-band processors for various applications (MATLAB, VHDL, IC)
 - Protocol processors in hardware and software (low latency, high throughput)

Future Activities (Outlook beyond 5G)



- Research on 6G is already ongoing
- Focus on higher frequency bands with unprecedented bandwidth
- Examples
 - D-Band (140 GHz) transceivers and waveforms
 - Extremely broadband transceiver from 110 – 170 GHz (6G-Kom project)
 - 240 GHz transceivers and scalable baseband processor + localization
 - Application for Augmented Reality in indoor scenario (WORTECS project)
 - High capacity, high cell density backhaul using mm-wave spectrum beyond 100 GHz
 - HORIZON2020 project ULTRAWAVE

Kontakt



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